# ACM Research Expands U.S. Operations with Oregon R&D and Manufacturing Facility as Part of $100 Million Investment

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## Facility strengthens U.S. capabilities, enhances support for North American customers and brings more jobs to the region

HILLSBORO, Ore., Nov. 17, 2026 (GLOBE NEWSWIRE) -- ACM Research, Inc. (“ACM”) (NASDAQ: ACMR), a leading supplier of wafer and panel processing solutions for semiconductor and advanced packaging applications, today announced the opening of its U.S. R&D and manufacturing facility in Hillsboro, Oregon. The facility marks a major milestone in Phase 1 of ACM’s plan to invest more than $100 million in its U.S. operations, advancing its mission to be a key supplier of world-class equipment to leading global semiconductor manufacturers.

The 40,000-square-foot facility includes a 24,000-square-foot production space and a world class demonstration lab. Bringing together equipment manufacturing, R&D and customer demonstration capabilities, the facility represents a significant step towards a comprehensive U.S. operation that supports technology development, equipment innovation and closer collaboration with North American customers.

“Since our founding in Silicon Valley in 1998, innovation in semiconductor process technology has been central to ACM’s growth into a global semiconductor equipment company,” said David Wang, President and CEO of ACM. “The opening of this Oregon facility represents an important milestone in our long-term strategy to strengthen our U.S. foundation while continuing to advance our global technology and manufacturing capabilities. Through this investment, we will expand our engineering and manufacturing presence in the U.S., work more closely with our domestic customers and contribute to the continued development of the U.S. semiconductor industry.”

The facility will provide North American customers closer access to ACM’s advanced wafer and panel processing technologies, including demonstration and evaluation capabilities for wet cleaning and electrochemical plating solutions used in front-end semiconductor manufacturing and advanced packaging. Integrating R&D, engineering, manufacturing and customer support at one location will also enable more direct incorporation of field feedback into equipment development, supporting continuous improvements in technology performance and quality. Expanded local parts sourcing and technical support capabilities are expected to improve service responsiveness, shorten parts replenishment times and help reduce mean time to repair.

Oregon has been an important part of ACM’s U.S. operations since the opening of its Hillsboro sales and service facility in 2023. This expansion marks the next phase of ACM’s investment in the region, building on its established presence within the Silicon Forest semiconductor ecosystem. With its concentration of semiconductor manufacturers, engineering talent and specialized suppliers, Oregon provides a strategic foundation for ACM to deepen its role in the U.S. semiconductor equipment supply chain and position itself for the next phase of growth in domestic semiconductor manufacturing.

**Forward-Looking Statements**

Certain statements contained in this press release are not historical facts and may be forward-looking statements within the meaning of the Private Securities Litigation Reform Act of 1995. Words such as “plans,” “expects,” “believes,” “anticipates,” “designed,” and similar words are intended to identify forward-looking statements. Forward-looking statements are based on ACM management’s current expectations and beliefs and involve a number of risks and uncertainties that are difficult to predict and that could cause actual results to differ materially from those stated or implied by the forward-looking statements. A description of certain of these risks, uncertainties and other matters can be found in filings ACM makes with the U.S. Securities and Exchange Commission, all of which are available at www.sec.gov. Because forward-looking statements involve risks and uncertainties, actual results and events may differ materially from results and events currently expected by ACM. Readers are cautioned not to place undue reliance on these forward-looking statements, which speak only as of the date hereof. ACM undertakes no obligation to publicly update these forward-looking statements to reflect events or circumstances that occur after the date hereof or to reflect any change in its expectations with regard to these forward-looking statements or the occurrence of unanticipated events.

**About ACM Research, Inc.**

ACM develops, manufactures and sells semiconductor process equipment spanning cleaning, electroplating, stress-free polishing, vertical furnace processes, track, PECVD, and wafer- and panel-level packaging tools, enabling advanced and semi-critical semiconductor device manufacturing. ACM is committed to delivering customized, high-performance, cost-effective process

solutions that semiconductor manufacturers can use in numerous manufacturing steps to improve productivity and product yield. For more information, visit www.acmr.com.

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